

AN APPARATUS AND A METHOD FOR CONTROLLING TEMPERATURE OF A HEATING ELEMENT IN A THERMOCOMPRESSION BONDING PROCESS

ABSTRACT

5 An apparatus and a method for controlling temperature of a heating element of a thermocompression bonding machine in a thermocompression bonding process is disclosed. An input temperature profile is applied to apply heat to the heating element in the thermocompression bonding machine. A controller of the thermocompression bonding machine can be configured to receive a heating element temperature signal corresponding
10 to a temperature of the heating element. A temperature compensation profile can be generated in the controller based on the heating element temperature signal and a input temperature signal corresponding to the input temperature profile. Power input to the heating element can be controlled in the controller based on the temperature compensation profile.

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[FIG. 8]